

RCE/2811

REQUEST FOR CONTINUED EXAMINATION (RCE) TRANSMITTAL

Subsection b of 35 U.S.C. § 132, effective on May 29, 2000, provides for the continued examination of a utility or plant application filed on or after June 8, 1995.

JAN 30 2003

Application Number	09/528,296
Filing Date	March 17, 2000
First Named Inventor	Kazuhiko TAKADA
Group Art Unit	2811
Name of Examiner	Ori NADAV
Attorney Docket No.	000294

This Request for Continued Examination (RCE) under 37 C.F.R. § 1.114 of the above-identified application.

Note: 37 C.F.R. § 1.114 is effective on May 29, 2000. If the above-identified application was filed prior to May 29, 2000, applicant may wish to consider filing a continued prosecution application (CPA) under 37 C.F.R. § 1.53 (PTO/SB/29) instead of a RCE to be eligible for the patent term adjustment provisions of the AIPA. See changes to Application Examination and Provisional Application Practice, Interim Rule, 65 Fed. Reg. 14865 (Mar 20, 2000) 1233 Off. Gazette Pat Office (April 11, 2000) which established RCE practice.

#18/RCE
2/4/03
RECEIVED
TECHNOLOGY CENTER 2800
FEB - 3 2003

1. Submission Required Under 37 C.F.R. § 1.114

- a. ☐ Previously submitted
- i. ☐ Consider the amendment(s)/reply under 37 C.F.R. § 1.116 previously filed on _____
(Any unentered amendment(s) referred to above will be entered)
- ii. ☐ Consider the arguments in the Appeal Brief or Reply Brief previously filed on _____
- iii. ☐ Other _____
- b. ☒ Enclosed
- i. ☒ Amendment (Preliminary)
- ii. ☐ Affidavit(s)/Declaration(s)
- iii. ☐ Information Disclosure Statement (IDS)
- iv. ☐ Other _____

2. Miscellaneous

- a. ☐ Suspension of Action on the above-identified application is requested under 37 C.F.R. § 1.103(c) for a period of _____ months.
(period shall not exceed three months; Fee under 37 C.F.R. § 1.17(i) required)
- b. ☐ Other _____

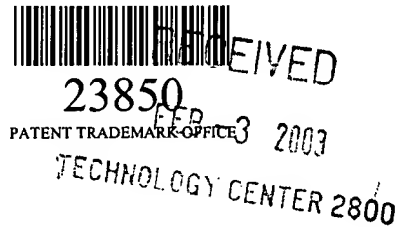
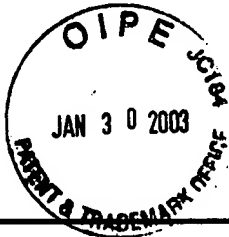
3. Fees The RCE fee under 37 C.F.R. § 1.17(e) is required by 37 C.F.R. § 1.114 when the RCE is filed.

- a. ☒ The Commissioner is hereby authorized to charge the following fees, or credit any overpayments, to Deposit Account No. 01-2340
- i. ☒ RCE fee required under 37 C.F.R. § 1.17 (e)
- ii. ☒ Extension of Time Fee (37 C.F.R. §§ 1.136 and 1.17)
- iii. ☐ Other _____
- b. ☒ Check in the amount of \$ 860.00 is enclosed including fees in the amount of \$750.00 for filing an RCE and \$110.00 for a Petition for a One-Month Extension of Time.

REQUEST FOR
CONTINUED EXAMINATION (RCE)
TRANSMITTAL

Subsection (b) of 35 U.S.C. § 132, effective on May 29, 2000, provides for the continued examination of a utility or plant application filed on or after June 8, 1995.

PAGE 2



Atty Docket No.

000294

SIGNATURE BY APPLICANT, ATTORNEY, OR AGENT REQUIRED

Name Joseph L. Felber

Registration No. 48,109

Signature

Date January 30, 2003

CERTIFICATE OF MAILING OR TRANSMISSION

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to Commissioner for Patents, BOX RCE, Washington, D.C. 20231, or facsimile transmitted to the U.S. Patent and Trademark Office on:

Name

Signature



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **TAKADA, Kazuhiko**

Serial No.: **09/528,296**

Filed: **March 17, 2000**

FOR: **SEMICONDUCTOR DEVICE HAVING A GUARD RING**

#19/D
2/4/03
RECEIVED
FEB - 3 2003
Abm/h

TECHNICAL UNIT 2811
Group Art Unit 2800

Examiner: **NADAV, Ori**

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Date: January 30, 2003

Sir:

Please amend as follows:

IN THE CLAIMS:

Cancel claim 5 without prejudice or disclaimer.

Amend the claim 1 as follows:

sub E1
D1

1. (Four Times Amended) A semiconductor device, comprising:
a substrate; and
a multilayer interconnection structure formed on said substrate,
said multilayer interconnection structure including: at least first and second interlayer
insulation films provided on said substrate; and a guard ring pattern embedded in each of said first
and second interlayer insulation films, said guard ring pattern extending along a periphery of said
substrate, said multilayer interconnection structure being planarized by using a CMP process,